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Details

Product Status	Obsolete
Core Processor	C166
Core Size	16-Bit
Speed	20MHz
Connectivity	EBI/EMI, SPI, UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	77
Program Memory Size	-
Program Memory Type	ROMless
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	PG-TQFP-100
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/c165lfhafxuma1

Revision History: 2000-12

V2.0

Previous Version:	1998-12	Update 0.5 μ technology
	01.96	3 Volt Addendum
	07.95	25 MHz Addendum
	09.94	Data Sheet

Page	Subjects (major changes since last revision)
All	Converted to Infineon layout
2	ROM derivatives removed, 25-MHz derivatives and 3 V derivatives included
6ff	Pin numbers for TQFP added
14	Address window arbitration and master/slave mode introduced
32	New standard layout for section "Absolute Maximum Ratings"
33	Section "Operating Conditions" added
34f	Parameter " $\overline{\text{RSTIN}}$ pullup" replaced by " $\overline{\text{RSTIN}}$ current"
36f	DC Characteristics for reduced supply voltage added
38f	Separate specification for power consumption with greatly improved values
40ff	Description of clock generation improved
45 , 55 , 65	Timing adapted to 25 MHz
48 , 58 , 66	Timing for reduced supply voltage added

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Any information within this document that you feel is wrong, unclear or missing at all?
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 Please send your proposal (including a reference to this document) to:

mcdocu.comments@infineon.com



This document describes several derivatives of the C165 group. **Table 1** enumerates these derivatives and summarizes the differences. As this document refers to all of these derivatives, some descriptions may not apply to a specific product.

Table 1 C165 Derivative Synopsis

Derivative ¹⁾	Max. Operating Frequency	Operating Voltage	Package
SAF-C165-LM	20 MHz	4.5 to 5.5 V	MQFP-100
SAB-C165-LM	20 MHz	4.5 to 5.5 V	MQFP-100
SAF-C165-L25M	25 MHz	4.5 to 5.5 V	MQFP-100
SAB-C165-L25M	25 MHz	4.5 to 5.5 V	MQFP-100
SAF-C165-LF	20 MHz	4.5 to 5.5 V	TQFP-100
SAB-C165-LF	20 MHz	4.5 to 5.5 V	TQFP-100
SAF-C165-L25F	25 MHz	4.5 to 5.5 V	TQFP-100
SAB-C165-L25F	25 MHz	4.5 to 5.5 V	TQFP-100
SAF-C165-LM3V	20 MHz	3.0 to 3.6 V	MQFP-100
SAB-C165-LM3V	20 MHz	3.0 to 3.6 V	MQFP-100
SAF-C165-LF3V	20 MHz	3.0 to 3.6 V	TQFP-100
SAB-C165-LF3V	20 MHz	3.0 to 3.6 V	TQFP-100

¹⁾ This Data Sheet is valid for devices starting with and including design step HA.

For simplicity all versions are referred to by the term **C165** throughout this document.

Ordering Information

The ordering code for Infineon microcontrollers provides an exact reference to the required product. This ordering code identifies:

- the derivative itself, i.e. its function set, the temperature range, and the supply voltage
- the package and the type of delivery.

For the available ordering codes for the C165 please refer to the “**Product Catalog Microcontrollers**”, which summarizes all available microcontroller variants.

Note: The ordering codes for Mask-ROM versions are defined for each product after verification of the respective ROM code.

Table 2 Pin Definitions and Functions

Symbol	Pin Nr TQFP	Pin Nr MQFP	Input Outp.	Function
XTAL1	5	7	I	XTAL1: Input to the oscillator amplifier and input to the internal clock generator
XTAL2	6	8	O	XTAL2: Output of the oscillator amplifier circuit. To clock the device from an external source, drive XTAL1, while leaving XTAL2 unconnected. Minimum and maximum high/low and rise/fall times specified in the AC Characteristics must be observed.
P3			IO	Port 3 is a 15-bit bidirectional I/O port. It is bit-wise programmable for input or output via direction bits. For a pin configured as input, the output driver is put into high-impedance state. Port 3 outputs can be configured as push/pull or open drain drivers. The Port 3 pins serve for following alternate functions:
P3.0	8	10		
P3.1	9	11	O	T6OUT GPT2 Timer T6 Toggle Latch Output
P3.2	10	12	I	CAPIN GPT2 Register CAPREL Capture Input
P3.3	11	13	O	T3OUT GPT1 Timer T3 Toggle Latch Output
P3.4	12	14	I	T3EUD GPT1 Timer T3 Ext. Up/Down Ctrl Input
P3.5	13	15	I	T4IN GPT1 Timer T4 Count/Gate/Reload/Capture Input
P3.6	14	16	I	T3IN GPT1 Timer T3 Count/Gate Input
P3.7	15	17	I	T2IN GPT1 Timer T2 Count/Gate/Reload/Capture Input
P3.8	16	18	I/O	MRST SSC Master-Receive/Slave-Transmit Input/Output
P3.9	17	19	I/O	MTSR SSC Master-Transmit/Slave-Receive Output/Input
P3.10	18	20	O	TxD0 ASC0 Clock/Data Output (Asyn./Sync.)
P3.11	19	21	I/O	RxD0 ASC0 Data Inp. (Asyn.) or In/Out (Sync)
P3.12	20	22	O	$\overline{\text{BHE}}$ Ext. Memory High Byte Enable Signal,
			O	$\overline{\text{WRH}}$ Ext. Memory High Byte Write Strobe
P3.13	21	23	I/O	SCLK SSC Master Cl. Output / Slave Cl. Input
P3.15	22	24	O	CLKOUT System Clock Output (= CPU Clock)

Functional Description

The architecture of the C165 combines advantages of both RISC and CISC processors and of advanced peripheral subsystems in a very well-balanced way. In addition the on-chip memory blocks allow the design of compact systems with maximum performance.

The following block diagram gives an overview of the different on-chip components and of the advanced, high bandwidth internal bus structure of the C165.

*Note: All time specifications refer to a CPU clock of 25 MHz
(see definition in the AC Characteristics section).*

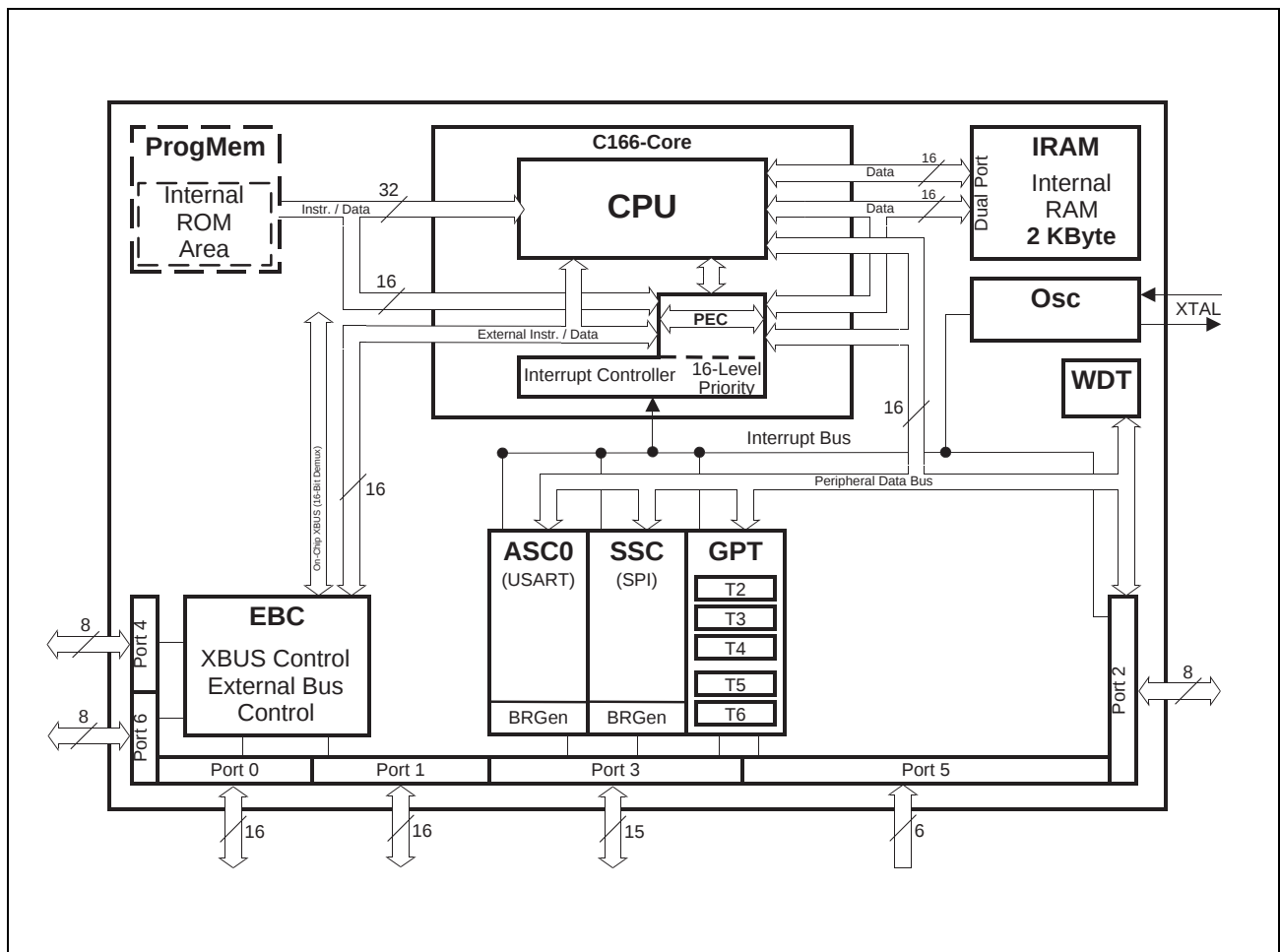


Figure 4 Block Diagram

The program memory, the internal RAM (IRAM) and the set of generic peripherals are connected to the CPU via separate buses. A fourth bus, the XBUS, connects external resources as well as additional on-chip resources, the X-Peripherals (see [Figure 4](#)).

Memory Organization

The memory space of the C165 is configured in a Von Neumann architecture which means that code memory, data memory, registers and I/O ports are organized within the same linear address space which includes 16 MBytes. The entire memory space can be accessed byte-wise or word-wise. Particular portions of the on-chip memory have additionally been made directly bit-addressable.

The C165 is prepared to incorporate on-chip program memory (not in the ROM-less derivatives, of course) for code or constant data. The internal ROM area can be mapped either to segment 0 or segment 1.

2 KBytes of on-chip Internal RAM (IRAM) are provided as a storage for user defined variables, for the system stack, general purpose register banks and even for code. A register bank can consist of up to 16 word-wide (R0 to R15) and/or byte-wide (RL0, RH0, ..., RL7, RH7) so-called General Purpose Registers (GPRs).

1024 bytes (2×512 bytes) of the address space are reserved for the Special Function Register areas (SFR space and ESFR space). SFRs are word-wide registers which are used for controlling and monitoring functions of the different on-chip units. Unused SFR addresses are reserved for future members of the C166 Family.

In order to meet the needs of designs where more memory is required than is provided on chip, up to 16 MBytes of external RAM and/or ROM can be connected to the microcontroller.

Central Processing Unit (CPU)

The main core of the CPU consists of a 4-stage instruction pipeline, a 16-bit arithmetic and logic unit (ALU) and dedicated SFRs. Additional hardware has been spent for a separate multiply and divide unit, a bit-mask generator and a barrel shifter.

Based on these hardware provisions, most of the C165's instructions can be executed in just one machine cycle which requires 80 ns at 25 MHz CPU clock. For example, shift and rotate instructions are always processed during one machine cycle independent of the number of bits to be shifted. All multiple-cycle instructions have been optimized so that they can be executed very fast as well: branches in 2 cycles, a 16×16 bit multiplication in 5 cycles and a 32-/16 bit division in 10 cycles. Another pipeline optimization, the so-called 'Jump Cache', allows reducing the execution time of repeatedly performed jumps in a loop from 2 cycles to 1 cycle.

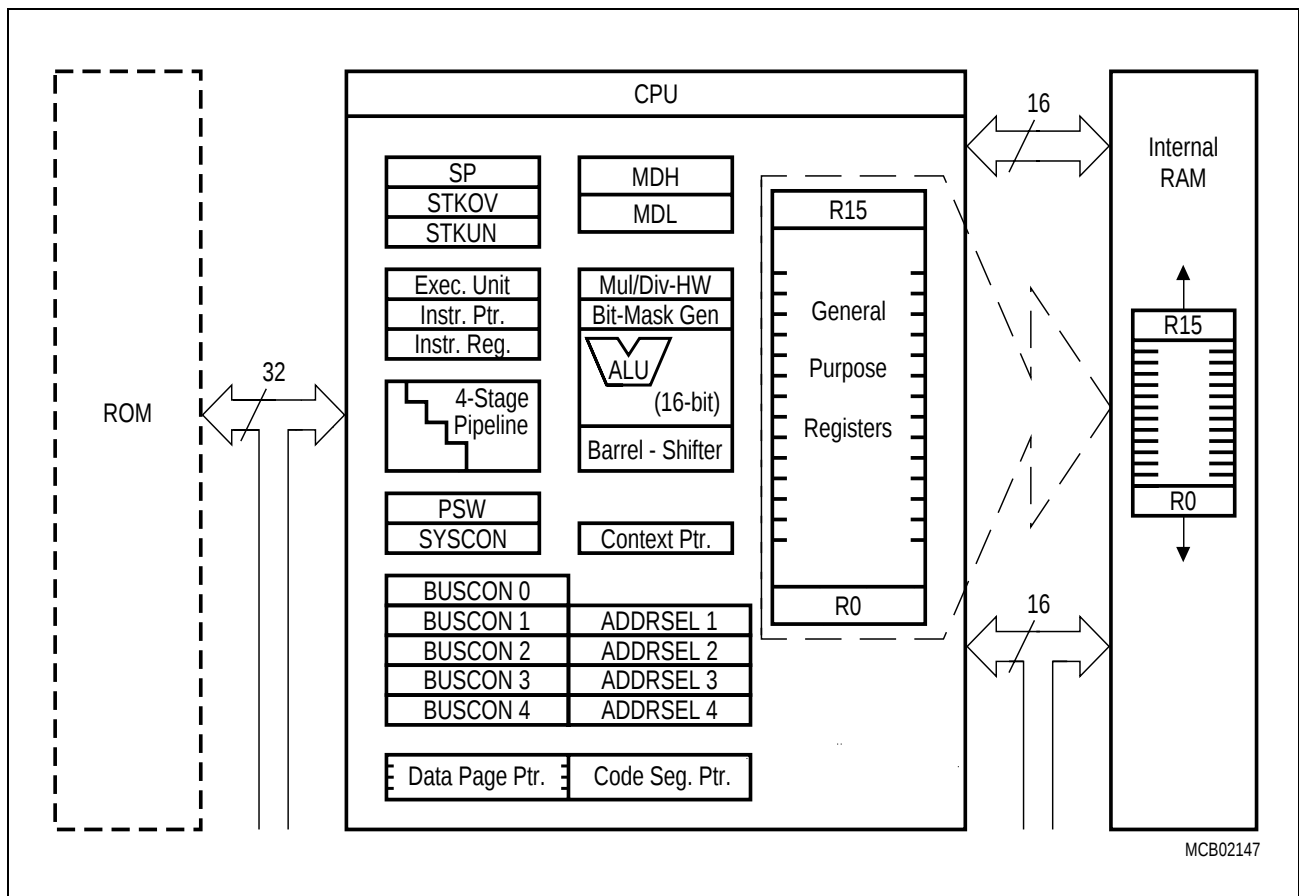


Figure 5 CPU Block Diagram

General Purpose Timer (GPT) Unit

The GPT unit represents a very flexible multifunctional timer/counter structure which may be used for many different time related tasks such as event timing and counting, pulse width and duty cycle measurements, pulse generation, or pulse multiplication.

The GPT unit incorporates five 16-bit timers which are organized in two separate modules, GPT1 and GPT2. Each timer in each module may operate independently in a number of different modes, or may be concatenated with another timer of the same module.

Each of the three timers T2, T3, T4 of **module GPT1** can be configured individually for one of four basic modes of operation, which are Timer, Gated Timer, Counter, and Incremental Interface Mode. In Timer Mode, the input clock for a timer is derived from the CPU clock, divided by a programmable prescaler, while Counter Mode allows a timer to be clocked in reference to external events.

Pulse width or duty cycle measurement is supported in Gated Timer Mode, where the operation of a timer is controlled by the 'gate' level on an external input pin. For these purposes, each timer has one associated port pin (TxIN) which serves as gate or clock input. The maximum resolution of the timers in module GPT1 is 16 TCL.

The count direction (up/down) for each timer is programmable by software or may additionally be altered dynamically by an external signal on a port pin (TxEUD) to facilitate e.g. position tracking.

In Incremental Interface Mode the GPT1 timers (T2, T3, T4) can be directly connected to the incremental position sensor signals A and B via their respective inputs TxIN and TxEUD. Direction and count signals are internally derived from these two input signals, so the contents of the respective timer Tx corresponds to the sensor position. The third position sensor signal TOP0 can be connected to an interrupt input.

Timer T3 has an output toggle latch (T3OTL) which changes its state on each timer overflow/underflow. The state of this latch may be output on pin T3OUT e.g. for time out monitoring of external hardware components, or may be used internally to clock timers T2 and T4 for measuring long time periods with high resolution.

In addition to their basic operating modes, timers T2 and T4 may be configured as reload or capture registers for timer T3. When used as capture or reload registers, timers T2 and T4 are stopped. The contents of timer T3 is captured into T2 or T4 in response to a signal at their associated input pins (TxIN). Timer T3 is reloaded with the contents of T2 or T4 triggered either by an external signal or by a selectable state transition of its toggle latch T3OTL. When both T2 and T4 are configured to alternately reload T3 on opposite state transitions of T3OTL with the low and high times of a PWM signal, this signal can be constantly generated without software intervention.

The capture trigger (timer T5 to CAPREL) may also be generated upon transitions of GPT1 timer T3's inputs T3IN and/or T3EUD. This is especially advantageous when T3 operates in Incremental Interface Mode.

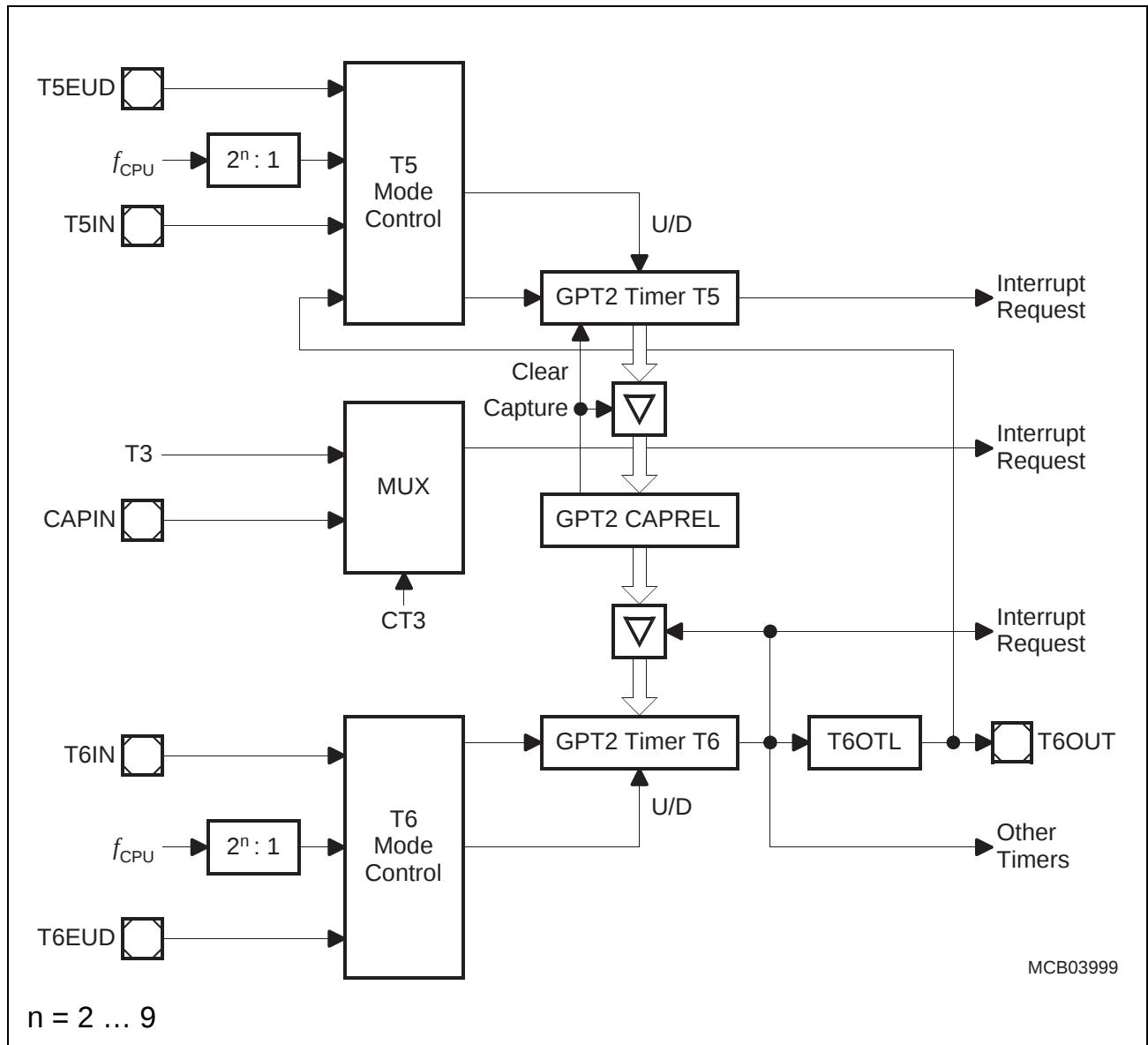


Figure 7 Block Diagram of GPT2

Watchdog Timer

The Watchdog Timer represents one of the fail-safe mechanisms which have been implemented to prevent the controller from malfunctioning for longer periods of time.

The Watchdog Timer is always enabled after a reset of the chip, and can only be disabled in the time interval until the EINIT (end of initialization) instruction has been executed. Thus, the chip's start-up procedure is always monitored. The software has to be designed to service the Watchdog Timer before it overflows. If, due to hardware or software related failures, the software fails to do so, the Watchdog Timer overflows and generates an internal hardware reset and pulls the $\overline{\text{RSTOUT}}$ pin low in order to allow external hardware components to be reset.

The Watchdog Timer is a 16-bit timer, clocked with the system clock divided by 2/128. The high byte of the Watchdog Timer register can be set to a prespecified reload value (stored in WDTREL) in order to allow further variation of the monitored time interval. Each time it is serviced by the application software, the high byte of the Watchdog Timer is reloaded. Thus, time intervals between 20 μs and 336 ms can be monitored (@ 25 MHz).

The default Watchdog Timer interval after reset is 5.24 ms (@ 25 MHz).

Parallel Ports

The C165 provides up to 77 I/O lines which are organized into six input/output ports and one input port. All port lines are bit-addressable, and all input/output lines are individually (bit-wise) programmable as inputs or outputs via direction registers. The I/O ports are true bidirectional ports which are switched to high impedance state when configured as inputs. The output drivers of three I/O ports can be configured (pin by pin) for push/pull operation or open-drain operation via control registers. During the internal reset, all port pins are configured as inputs.

All port lines have programmable alternate input or output functions associated with them. All port lines that are not used for these alternate functions may be used as general purpose IO lines.

PORT0 and PORT1 may be used as address and data lines when accessing external memory, while Port 4 outputs the additional segment address bits A23/19/17 ... A16 in systems where segmentation is enabled to access more than 64 KBytes of memory.

Port 6 provides optional chip select signals.

Port 3 includes alternate functions of timers, serial interfaces, the optional bus control signal $\overline{\text{BHE}}/\overline{\text{WRH}}$, and the system clock output CLKOUT.

Port 5 is used for timer control signals.

Special Function Registers Overview

The following table lists all SFRs which are implemented in the C165 in alphabetical order.

Bit-addressable SFRs are marked with the letter “b” in column “Name”. SFRs within the **Extended SFR-Space** (ESFRs) are marked with the letter “E” in column “Physical Address”. Registers within on-chip X-peripherals are marked with the letter “X” in column “Physical Address”.

An SFR can be specified via its individual mnemonic name. Depending on the selected addressing mode, an SFR can be accessed via its physical address (using the Data Page Pointers), or via its short 8-bit address (without using the Data Page Pointers).

Table 6 C165 Registers, Ordered by Name

Name	Physical Address	8-Bit Addr.	Description	Reset Value
ADDRSEL1	FE18 _H	0C _H	Address Select Register 1	0000 _H
ADDRSEL2	FE1A _H	0D _H	Address Select Register 2	0000 _H
ADDRSEL3	FE1C _H	0E _H	Address Select Register 3	0000 _H
ADDRSEL4	FE1E _H	0F _H	Address Select Register 4	0000 _H
BUSCON0 b	FF0C _H	86 _H	Bus Configuration Register 0	0XX0 _H
BUSCON1 b	FF14 _H	8A _H	Bus Configuration Register 1	0000 _H
BUSCON2 b	FF16 _H	8B _H	Bus Configuration Register 2	0000 _H
BUSCON3 b	FF18 _H	8C _H	Bus Configuration Register 3	0000 _H
BUSCON4 b	FF1A _H	8D _H	Bus Configuration Register 4	0000 _H
CAPREL	FE4A _H	25 _H	GPT2 Capture/Reload Register	0000 _H
CC10IC b	FF8C _H	C6 _H	EX2IN Interrupt Control Register	0000 _H
CC11IC b	FF8E _H	C7 _H	EX3IN Interrupt Control Register	0000 _H
CC12IC b	FF90 _H	C8 _H	EX4IN Interrupt Control Register	0000 _H
CC13IC b	FF92 _H	C9 _H	EX5IN Interrupt Control Register	0000 _H
CC14IC b	FF94 _H	CA _H	EX6IN Interrupt Control Register	0000 _H
CC15IC b	FF96 _H	CB _H	EX7IN Interrupt Control Register	0000 _H
CC29IC b	F184 _H E	C2 _H	Software Interrupt Control Register	0000 _H
CC30IC b	F18C _H E	C6 _H	Software Interrupt Control Register	0000 _H
CC31IC b	F194 _H E	CA _H	Software Interrupt Control Register	0000 _H
CC8IC b	FF88 _H	C4 _H	EX0IN Interrupt Control Register	0000 _H
CC9IC b	FF8A _H	C5 _H	EX1IN Interrupt Control Register	0000 _H

DC Characteristics (Reduced Supply Voltage Range)

(Operating Conditions apply)¹⁾

Parameter	Symbol	Limit Values		Unit	Test Condition
		min.	max.		
Input low voltage (TTL, all except XTAL1)	V_{IL} SR	- 0.5	0.8	V	–
Input low voltage XTAL1	V_{IL2} SR	- 0.5	$0.3 V_{DD}$	V	–
Input high voltage (TTL, all except $\overline{RSTIN}$ and XTAL1)	V_{IH} SR	1.8	$V_{DD} + 0.5$	V	–
Input high voltage $\overline{RSTIN}$ (when operated as input)	V_{IH1} SR	$0.6 V_{DD}$	$V_{DD} + 0.5$	V	–
Input high voltage XTAL1	V_{IH2} SR	$0.7 V_{DD}$	$V_{DD} + 0.5$	V	–
Output low voltage (PORT0, PORT1, Port 4, ALE, $\overline{RD}$, $\overline{WR}$, $\overline{BHE}$, $\overline{RSTOUT}$, $\overline{RSTIN}^{2)}$)	V_{OL} CC	–	0.45	V	$I_{OL} = 1.6 \text{ mA}$
Output low voltage (all other outputs)	V_{OL1} CC	–	0.45	V	$I_{OL} = 1.0 \text{ mA}$
Output high voltage ³⁾ (PORT0, PORT1, Port 4, ALE, $\overline{RD}$, $\overline{WR}$, $\overline{BHE}$, $\overline{RSTOUT}$)	V_{OH} CC	$0.9 V_{DD}$	–	V	$I_{OH} = - 0.5 \text{ mA}$
Output high voltage ³⁾ (all other outputs)	V_{OH1} CC	$0.9 V_{DD}$	–	V	$I_{OH} = - 0.25 \text{ mA}$
Input leakage current (Port 5)	I_{OZ1} CC	–	± 200	nA	$0 \text{ V} < V_{IN} < V_{DD}$
Input leakage current (all other)	I_{OZ2} CC	–	± 500	nA	$0.45 \text{ V} < V_{IN} < V_{DD}$
$\overline{RSTIN}$ inactive current ⁴⁾	$I_{RSTH}^{5)}$	–	- 10	μA	$V_{IN} = V_{IH1}$
$\overline{RSTIN}$ active current ⁴⁾	$I_{RSTL}^{6)}$	- 100	–	μA	$V_{IN} = V_{IL}$
$\overline{READY}/\overline{RD}/\overline{WR}$ inact. current ⁷⁾	$I_{RWH}^{5)}$	–	- 10	μA	$V_{OUT} = 2.4 \text{ V}$
$\overline{READY}/\overline{RD}/\overline{WR}$ active current ⁷⁾	$I_{RWL}^{6)}$	- 500	–	μA	$V_{OUT} = V_{OLmax}$
ALE inactive current ⁷⁾	$I_{ALEL}^{5)}$	–	20	μA	$V_{OUT} = V_{OLmax}$
ALE active current ⁷⁾	$I_{ALEH}^{6)}$	500	–	μA	$V_{OUT} = 2.4 \text{ V}$
Port 6 inactive current ⁷⁾	$I_{P6H}^{5)}$	–	- 10	μA	$V_{OUT} = 2.4 \text{ V}$
Port 6 active current ⁷⁾	$I_{P6L}^{6)}$	- 500	–	μA	$V_{OUT} = V_{OL1max}$

DC Characteristics (Reduced Supply Voltage Range) (cont'd)

(Operating Conditions apply)¹⁾

Parameter	Symbol	Limit Values		Unit	Test Condition
		min.	max.		
PORT0 configuration current ⁸⁾	I_{P0H} ⁵⁾	–	- 5	μA	$V_{IN} = V_{IHmin}$
	I_{P0L} ⁶⁾	- 100	–	μA	$V_{IN} = V_{ILmax}$
XTAL1 input current	I_{IL} CC	–	± 20	μA	$0\text{ V} < V_{IN} < V_{DD}$
Pin capacitance ⁹⁾ (digital inputs/outputs)	C_{IO} CC	–	10	pF	$f = 1\text{ MHz}$ $T_A = 25\text{ °C}$

¹⁾ Keeping signal levels within the levels specified in this table, ensures operation without overload conditions. For signal levels outside these specifications also refer to the specification of the overload current I_{OV} .

²⁾ Valid in bidirectional reset mode only.

³⁾ This specification is not valid for outputs which are switched to open drain mode. In this case the respective output will float and the voltage results from the external circuitry.

⁴⁾ These parameters describe the $\overline{RSTIN}$ pullup, which equals a resistance of ca. 50 to 250 kΩ.

⁵⁾ The maximum current may be drawn while the respective signal line remains inactive.

⁶⁾ The minimum current must be drawn in order to drive the respective signal line active.

⁷⁾ This specification is valid during Reset and during Hold-mode or Adapt-mode. During Hold-mode Port 6 pins are only affected, if they are used (configured) for $\overline{CS}$ output and the open drain function is not enabled. The $\overline{READY}$ -pullup is always active, except for Powerdown mode.

⁸⁾ This specification is valid during Reset and during Adapt-mode.

⁹⁾ Not 100% tested, guaranteed by design and characterization.

Power Consumption C165 (Standard Supply Voltage Range)

(Operating Conditions apply)

Parameter	Symbol	Limit Values		Unit	Test Condition
		min.	max.		
Power supply current (active) with all peripherals active	I_{DD5}	–	$15 + 1.8 \times f_{CPU}$	mA	$\overline{RSTIN} = V_{IL}$ f_{CPU} in [MHz] ¹⁾
Idle mode supply current with all peripherals active	I_{IDX5}	–	$2 + 0.4 \times f_{CPU}$	mA	$\overline{RSTIN} = V_{IH1}$ f_{CPU} in [MHz] ¹⁾
Power-down mode supply current	I_{PDO5}	–	50	μA	$V_{DD} = V_{DDmax}$ ²⁾

- ¹⁾ The supply current is a function of the operating frequency. This dependency is illustrated in [Figure 8](#). These parameters are tested at V_{DDmax} and maximum CPU clock with all outputs disconnected and all inputs at V_{IL} or V_{IH} .
- ²⁾ This parameter is tested including leakage currents. All inputs (including pins configured as inputs) at 0 V to 0.1 V or at $V_{DD} - 0.1$ V to V_{DD} , all outputs (including pins configured as outputs) disconnected.

Power Consumption C165 (Reduced Supply Voltage Range)

(Operating Conditions apply)

Parameter	Symbol	Limit Values		Unit	Test Condition
		min.	max.		
Power supply current (active) with all peripherals active	I_{DD3}	–	$3 + 1.3 \times f_{CPU}$	mA	$\overline{RSTIN} = V_{IL}$ f_{CPU} in [MHz] ¹⁾
Idle mode supply current with all peripherals active	I_{IDX3}	–	$1 + 0.4 \times f_{CPU}$	mA	$\overline{RSTIN} = V_{IH1}$ f_{CPU} in [MHz] ¹⁾
Power-down mode supply current	I_{PDO3}	–	30	μA	$V_{DD} = V_{DDmax}$ ²⁾

- ¹⁾ The supply current is a function of the operating frequency. This dependency is illustrated in [Figure 8](#). These parameters are tested at V_{DDmax} and maximum CPU clock with all outputs disconnected and all inputs at V_{IL} or V_{IH} .
- ²⁾ This parameter is tested including leakage currents. All inputs (including pins configured as inputs) at 0 V to 0.1 V or at $V_{DD} - 0.1$ V to V_{DD} , all outputs (including pins configured as outputs) disconnected.

AC Characteristics

Definition of Internal Timing

The internal operation of the C165 is controlled by the internal CPU clock f_{CPU} . Both edges of the CPU clock can trigger internal (e.g. pipeline) or external (e.g. bus cycles) operations.

The specification of the external timing (AC Characteristics) therefore depends on the time between two consecutive edges of the CPU clock, called "TCL" (see [Figure 9](#)).

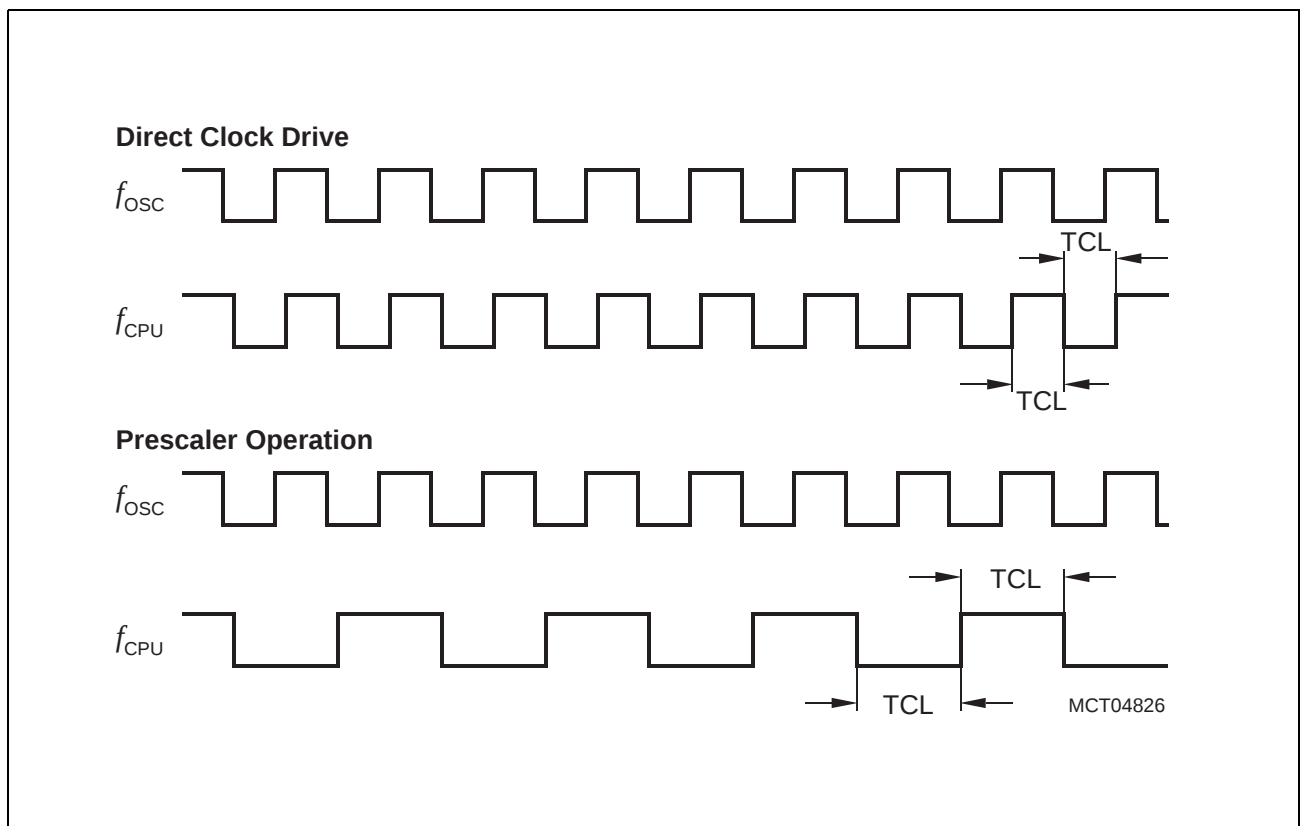


Figure 9 Generation Mechanisms for the CPU Clock

The CPU clock signal f_{CPU} can be generated from the oscillator clock signal f_{OSC} via different mechanisms. The duration of TCLs and their variation (and also the derived external timing) depends on the used mechanism to generate f_{CPU} . This influence must be regarded when calculating the timings for the C165.

The used mechanism to generate the basic CPU clock is selected by bitfield CLKCFG in register RP0H.7-5. Upon a long hardware reset register RP0H is loaded with the logic levels present on the upper half of PORT0 (P0H), i.e. bitfield CLKCFG represents the logic levels on pins P0.15-13 (P0H.7-5).

Table 9 associates the combinations of these three bits with the respective clock generation mode.

Multiplexed Bus (Reduced Supply Voltage Range) (cont'd)

(Operating Conditions apply)

ALE cycle time = 6 TCL + t_A + t_C + t_F (150 ns at 20 MHz CPU clock without waitstates)

Parameter	Symbol	Max. CPU Clock = 20 MHz		Variable CPU Clock 1 / 2TCL = 1 to 20 MHz		Unit
		min.	max.	min.	max.	
Data float after $\overline{RD}$	t_{19} SR	–	$36 + t_F$	–	$2TCL - 14 + t_F$	ns
Data valid to $\overline{WR}$	t_{22} CC	$24 + t_C$	–	$2TCL - 26 + t_C$	–	ns
Data hold after $\overline{WR}$	t_{23} CC	$36 + t_F$	–	$2TCL - 14 + t_F$	–	ns
ALE rising edge after $\overline{RD}$, $\overline{WR}$	t_{25} CC	$36 + t_F$	–	$2TCL - 14 + t_F$	–	ns
Address hold after $\overline{RD}$, $\overline{WR}$	t_{27} CC	$36 + t_F$	–	$2TCL - 14 + t_F$	–	ns
ALE falling edge to $\overline{CS}^{1)}$	t_{38} CC	$-8 - t_A$	$10 - t_A$	$-8 - t_A$	$10 - t_A$	ns
$\overline{CS}$ low to Valid Data In ¹⁾	t_{39} SR	–	$47 + t_C + 2t_A$	–	$3TCL - 28 + t_C + 2t_A$	ns
$\overline{CS}$ hold after $\overline{RD}$, $\overline{WR}^{1)}$	t_{40} CC	$57 + t_F$	–	$3TCL - 18 + t_F$	–	ns
ALE fall. edge to $\overline{RdCS}$, $\overline{WrCS}$ (with RW delay)	t_{42} CC	$19 + t_A$	–	$TCL - 6 + t_A$	–	ns
ALE fall. edge to $\overline{RdCS}$, $\overline{WrCS}$ (no RW delay)	t_{43} CC	$-6 + t_A$	–	$-6 + t_A$	–	ns
Address float after $\overline{RdCS}$, $\overline{WrCS}$ (with RW delay)	t_{44} CC	–	0	–	0	ns
Address float after $\overline{RdCS}$, $\overline{WrCS}$ (no RW delay)	t_{45} CC	–	25	–	TCL	ns
$\overline{RdCS}$ to Valid Data In (with RW delay)	t_{46} SR	–	$20 + t_C$	–	$2TCL - 30 + t_C$	ns
$\overline{RdCS}$ to Valid Data In (no RW delay)	t_{47} SR	–	$45 + t_C$	–	$3TCL - 30 + t_C$	ns
$\overline{RdCS}$, $\overline{WrCS}$ Low Time (with RW delay)	t_{48} CC	$38 + t_C$	–	$2TCL - 12 + t_C$	–	ns
$\overline{RdCS}$, $\overline{WrCS}$ Low Time (no RW delay)	t_{49} CC	$63 + t_C$	–	$3TCL - 12 + t_C$	–	ns

AC Characteristics

Demultiplexed Bus (Reduced Supply Voltage Range)

(Operating Conditions apply)

ALE cycle time = $4 \text{ TCL} + 2t_A + t_C + t_F$ (100 ns at 20 MHz CPU clock without waitstates)

Parameter	Symbol	Max. CPU Clock = 20 MHz		Variable CPU Clock 1 / 2TCL = 1 to 20 MHz		Unit
		min.	max.	min.	max.	
ALE high time	t_5 CC	$11 + t_A$	–	$\text{TCL} - 14 + t_A$	–	ns
Address setup to ALE	t_6 CC	$5 + t_A$	–	$\text{TCL} - 20 + t_A$	–	ns
ALE falling edge to $\overline{\text{RD}}$, $\overline{\text{WR}}$ (with RW-delay)	t_8 CC	$15 + t_A$	–	$\text{TCL} - 10 + t_A$	–	ns
ALE falling edge to $\overline{\text{RD}}$, $\overline{\text{WR}}$ (no RW-delay)	t_9 CC	$-10 + t_A$	–	$-10 + t_A$	–	ns
$\overline{\text{RD}}$, $\overline{\text{WR}}$ low time (with RW-delay)	t_{12} CC	$34 + t_C$	–	$2\text{TCL} - 16 + t_C$	–	ns
$\overline{\text{RD}}$, $\overline{\text{WR}}$ low time (no RW-delay)	t_{13} CC	$59 + t_C$	–	$3\text{TCL} - 16 + t_C$	–	ns
$\overline{\text{RD}}$ to valid data in (with RW-delay)	t_{14} SR	–	$22 + t_C$	–	$2\text{TCL} - 28 + t_C$	ns
$\overline{\text{RD}}$ to valid data in (no RW-delay)	t_{15} SR	–	$47 + t_C$	–	$3\text{TCL} - 28 + t_C$	ns
ALE low to valid data in	t_{16} SR	–	$45 + t_A + t_C$	–	$3\text{TCL} - 30 + t_A + t_C$	ns
Address to valid data in	t_{17} SR	–	$57 + 2t_A + t_C$	–	$4\text{TCL} - 43 + 2t_A + t_C$	ns
Data hold after $\overline{\text{RD}}$ rising edge	t_{18} SR	0	–	0	–	ns
Data float after $\overline{\text{RD}}$ rising edge (with RW-delay ¹⁾)	t_{20} SR	–	$36 + 2t_A + t_F^{(1)}$	–	$2\text{TCL} - 14 + 22t_A + t_F^{(1)}$	ns
Data float after $\overline{\text{RD}}$ rising edge (no RW-delay ¹⁾)	t_{21} SR	–	$15 + 2t_A + t_F^{(1)}$	–	$\text{TCL} - 10 + 22t_A + t_F^{(1)}$	ns

Demultiplexed Bus (Reduced Supply Voltage Range) (cont'd)

(Operating Conditions apply)

ALE cycle time = 4 TCL + 2t_A + t_C + t_F (100 ns at 20 MHz CPU clock without waitstates)

Parameter	Symbol	Max. CPU Clock = 20 MHz		Variable CPU Clock 1 / 2TCL = 1 to 20 MHz		Unit
		min.	max.	min.	max.	
Data valid to $\overline{WR}$	t ₂₂ CC	24 + t _C	–	2TCL - 26 + t _C	–	ns
Data hold after $\overline{WR}$	t ₂₄ CC	15 + t _F	–	TCL - 10 + t _F	–	ns
ALE rising edge after $\overline{RD}$, $\overline{WR}$	t ₂₆ CC	- 12 + t _F	–	- 12 + t _F	–	ns
Address hold after $\overline{WR}$ ²⁾	t ₂₈ CC	0 + t _F	–	0 + t _F	–	ns
ALE falling edge to $\overline{CS}$ ³⁾	t ₃₈ CC	- 8 - t _A	10 - t _A	- 8 - t _A	10 - t _A	ns
$\overline{CS}$ low to Valid Data In ³⁾	t ₃₉ SR	–	47 + t _C + 2t _A	–	3TCL - 28 + t _C + 2t _A	ns
$\overline{CS}$ hold after $\overline{RD}$, $\overline{WR}$ ³⁾	t ₄₁ CC	9 + t _F	–	TCL - 16 + t _F	–	ns
ALE falling edge to $\overline{RdCS}$, $\overline{WrCS}$ (with RW- delay)	t ₄₂ CC	19 + t _A	–	TCL - 6 + t _A	–	ns
ALE falling edge to $\overline{RdCS}$, $\overline{WrCS}$ (no RW- delay)	t ₄₃ CC	- 6 + t _A	–	- 6 + t _A	–	ns
$\overline{RdCS}$ to Valid Data In (with RW-delay)	t ₄₆ SR	–	20 + t _C	–	2TCL - 30 + t _C	ns
$\overline{RdCS}$ to Valid Data In (no RW-delay)	t ₄₇ SR	–	45 + t _C	–	3TCL - 30 + t _C	ns
$\overline{RdCS}$, $\overline{WrCS}$ Low Time (with RW-delay)	t ₄₈ CC	38 + t _C	–	2TCL - 12 + t _C	–	ns
$\overline{RdCS}$, $\overline{WrCS}$ Low Time (no RW-delay)	t ₄₉ CC	63 + t _C	–	3TCL - 12 + t _C	–	ns
Data valid to $\overline{WrCS}$	t ₅₀ CC	28 + t _C	–	2TCL - 22 + t _C	–	ns
Data hold after $\overline{RdCS}$	t ₅₁ SR	0	–	0	–	ns

Demultiplexed Bus (Reduced Supply Voltage Range) (cont'd)

(Operating Conditions apply)

ALE cycle time = $4 \text{ TCL} + 2t_A + t_C + t_F$ (100 ns at 20 MHz CPU clock without waitstates)

Parameter	Symbol	Max. CPU Clock = 20 MHz		Variable CPU Clock 1 / 2TCL = 1 to 20 MHz		Unit
		min.	max.	min.	max.	
Data float after $\overline{\text{RdCS}}$ (with RW-delay) ¹⁾	t_{53} SR	–	$30 + t_F$	–	$2\text{TCL} - 20 + 2t_A + t_F$ 1)	ns
Data float after $\overline{\text{RdCS}}$ (no RW-delay) ¹⁾	t_{68} SR	–	$5 + t_F$	–	$\text{TCL} - 20 + 2t_A + t_F$ 1)	ns
Address hold after $\overline{\text{RdCS}}$, $\overline{\text{WrCS}}$	t_{55} CC	$-16 + t_F$	–	$-16 + t_F$	–	ns
Data hold after $\overline{\text{WrCS}}$	t_{57} CC	$9 + t_F$	–	$\text{TCL} - 16 + t_F$	–	ns

¹⁾ RW-delay and t_A refer to the next following bus cycle (including an access to an on-chip X-Peripheral).

²⁾ Read data are latched with the same clock edge that triggers the address change and the rising $\overline{\text{RD}}$ edge. Therefore address changes before the end of $\overline{\text{RD}}$ have no impact on read cycles.

³⁾ These parameters refer to the latched chip select signals ($\overline{\text{CSxL}}$). The early chip select signals ($\overline{\text{CSxE}}$) are specified together with the address and signal $\overline{\text{BHE}}$ (see figures below).

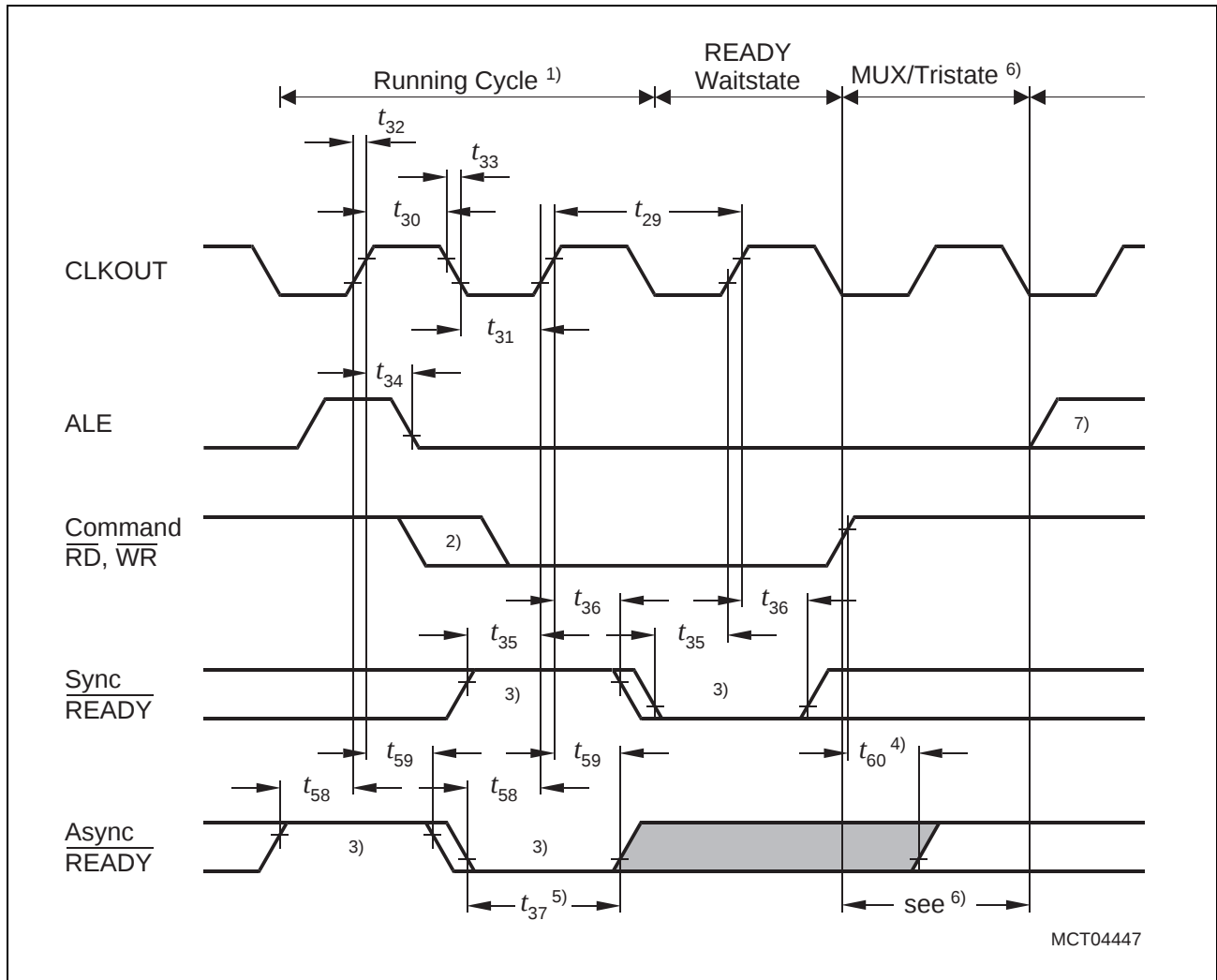
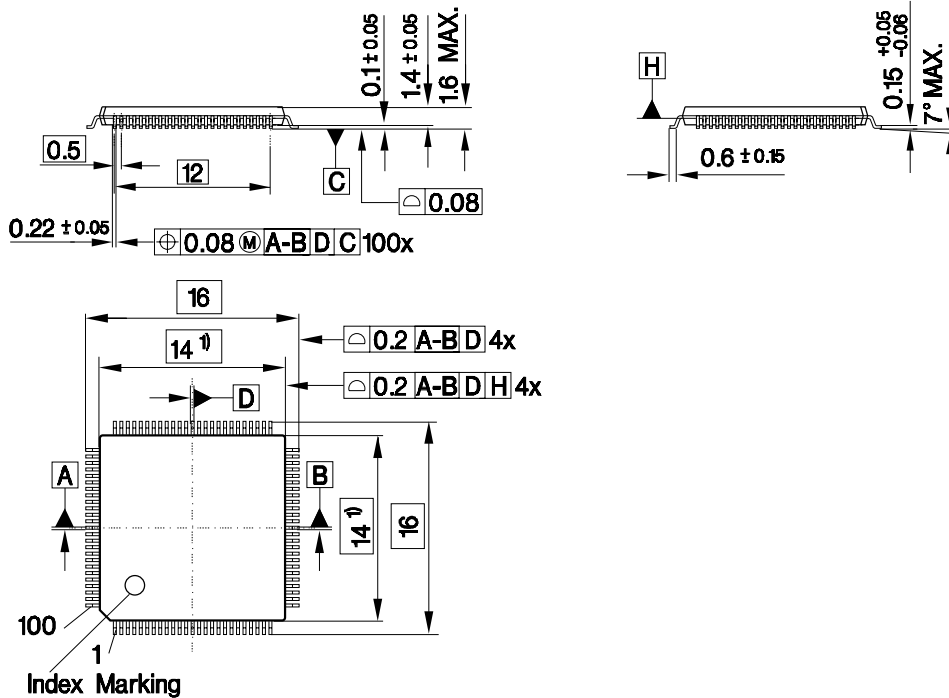


Figure 21 CLKOUT and $\overline{\text{READY}}$

Notes

- 1) Cycle as programmed, including MCTC waitstates (Example shows 0 MCTC WS).
- 2) The leading edge of the respective command depends on RW-delay.
- 3) $\overline{\text{READY}}$ sampled HIGH at this sampling point generates a $\overline{\text{READY}}$ controlled waitstate, $\overline{\text{READY}}$ sampled LOW at this sampling point terminates the currently running bus cycle.
- 4) $\overline{\text{READY}}$ may be deactivated in response to the trailing (rising) edge of the corresponding command ($\overline{\text{RD}}$ or $\overline{\text{WR}}$).
- 5) If the Asynchronous $\overline{\text{READY}}$ signal does not fulfill the indicated setup and hold times with respect to CLKOUT (e.g. because CLKOUT is not enabled), it must fulfill t_{37} in order to be safely synchronized. This is guaranteed, if $\overline{\text{READY}}$ is removed in response to the command (see Note 4)).
- 6) Multiplexed bus modes have a MUX waitstate added after a bus cycle, and an additional MTTC waitstate may be inserted here.
For a multiplexed bus with MTTC waitstate this delay is 2 CLKOUT cycles, for a demultiplexed bus without MTTC waitstate this delay is zero.
- 7) The next external bus cycle may start here.

P-TQFP-100 (SMD) (Plastic Thin Metric Quad Flat Package)



GPP05614

Sorts of Packing

Package outlines for tubes, trays etc. are contained in our Data Book "Package Information".

SMD = Surface Mounted Device

Dimensions in mm